

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****RECEIVED****CENTRAL FAX CENTER**

In re application of: Wang et al.

Attorney Docket No.:  
ALTRP100/A1198**JAN 29 2008**

Application No.: 10/719,218

Examiner: Rao, Shrinivas H.

Filed: November 20, 2003

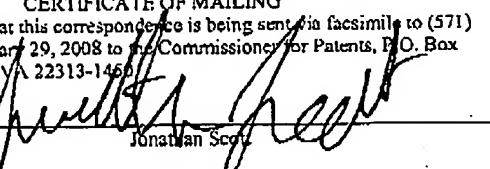
Group: 2814

Title: STRUCTURE, MATERIAL, AND DESIGN  
FOR ASSEMBLING A LOW-K SI DIE TO  
ACHIEVE AN INDUSTRIAL GRADE  
RELIABILITY WIRE BONDING PACKAGE

Confirmation No.: 3208

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being sent via facsimile to (571)  
273-8300 on January 29, 2008 to the Commissioner for Patents, P.O. Box  
1450 Alexandria, VA 22313-1450

Signed:   
Jonathan Scott**AMENDMENT F**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 29, 2007, please amend the above-identified patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begin on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.